



- Thin-film substrate-based microstrip circulator
- Discrete on chip load termination integrated on common backplane
- Small size, low profile & light weight
- Low insertion loss and high isolation
- No tuning required
- Designed for space applications
- RoHS compliant

| Parameter | Standard Value | Remark |
|--------------------------------|---|--|
| Product Type | Isolator | |
| Configuration | Drop in circulator with discrete load termination | |
| Frequency Range | 8.8 to 10.4 GHz | |
| Forward Power | 3 W | |
| Reverse Power | 50% | |
| Insertion Loss | ≤ 0.5 dB | 75°C max. |
| VSWR | ≤ 1.25 | 75°C max. |
| Isolation | ≥ 20 dB | 75°C max. |
| RF Waveguide | Microstrip line, 50 Ω | |
| RF Flanges / Connectors | Bond pads for Au-wire or ribbon bonding | bonding areas free of scratches |
| | Backplane for adhesive Ag-epoxy bonding | |
| Metallization | Au (5µm) | on top and bottom of ferrite substrate |
| | Au (1µm) | on backplane |
| Temperature Range | -30°C to +110°C | operating |
| | -55°C to +125°C | storage |
| | +150°C for 2 hours | assembly |
| Dimensions | 11.94 x 10.67 mm ² | |
| Height | 2.0 mm max. | |
| Substrate thickness | 0.65 mm ± 0.05mm | including backplane |
| Footprint Drawing | FP-10075179A | |
| Comment | no tuning or ferrite surface scratching allowed | |

| Rev. | Remark | Date | Name |
|------|-------------------------|------------|---------|
| 00 | Initial | 11.07.2017 | C. Weil |
| 01 | Ferrite substrate shape | 27.01.2022 | C. Weil |